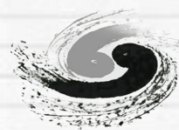


Digitization of TaichuPix-3 silicon pixel detector based on AllPix-Squared framework

Author: Hancen LU, Shuqi LI, Zhijun LIANG

Reporter: Hancen LU



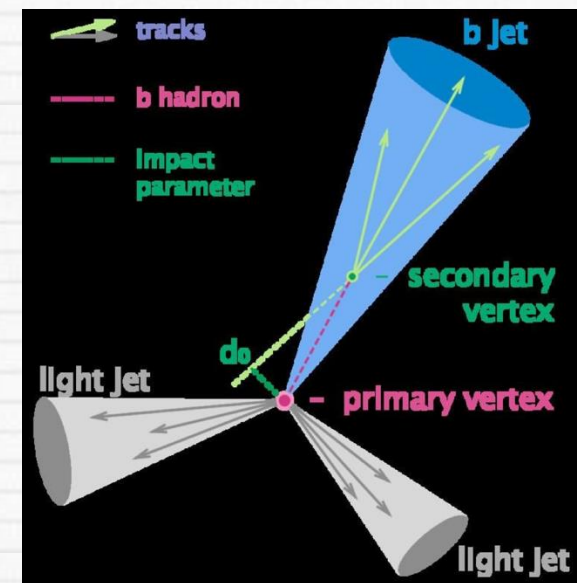
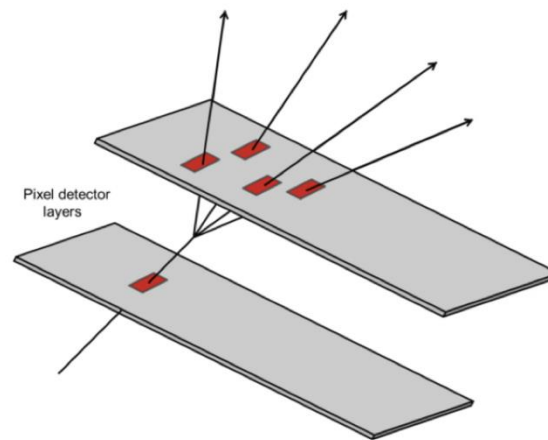
High-precision vertex detectors are crucial for the realization of the CEPC physics goals

- Flavor physics (a large number of b/c quark jets, τ leptons)
- Higgs physics ($H \rightarrow bb/cc/gg$ and $H \rightarrow \tau\tau$)

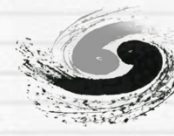
Goal: $\sigma(\text{IP}) \sim 5\mu\text{m}$ for high P track

CDR design specifications

- Single point resolution $\sim 3\mu\text{m}$
- Low material ($0.15\% X_0/\text{Layer}$)
- Low power ($< 50\text{mW}/\text{cm}^2$)
- Radiation hard (1 Mrad/year)



Intro: TaichuPix-3



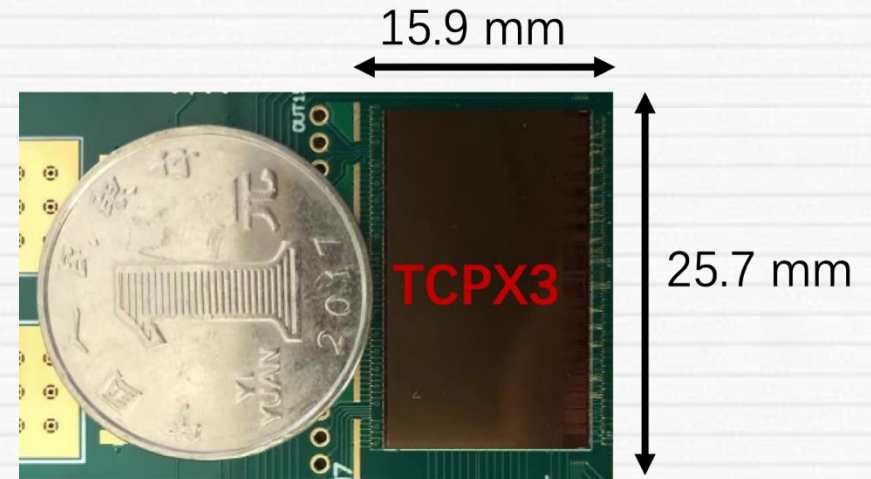
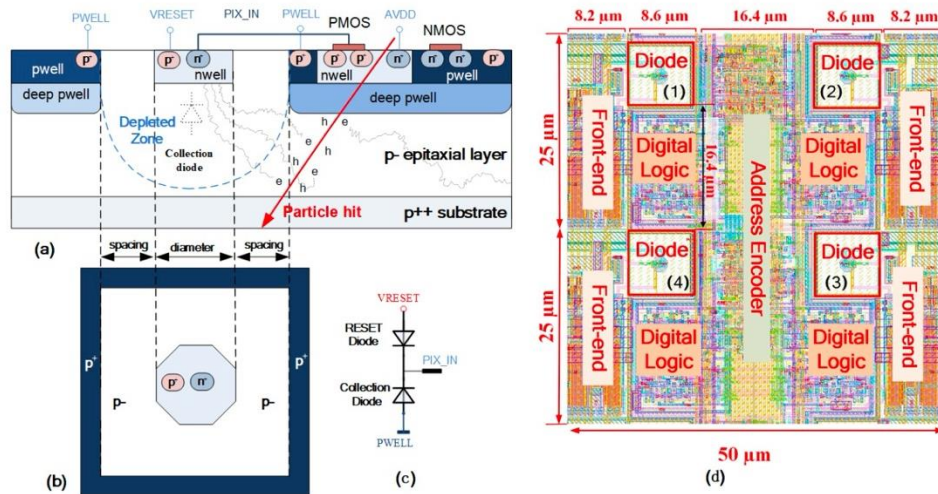
Requirements of the CEPC for VXD

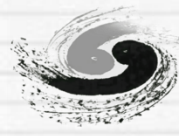
CEPC VXD team

TaichuPix

- Data-driven
- Fast-readout
- monolithic active

Specification	Index
Pixel size	25 μm \times 25 μm
Dimension	15.9 mm \times 25.7 mm
Techonology	CIS 180 nm
Dead time	< 500 ns
Power density	< 200 mW cm^{-2}
Max. hit rate	$36 \times 10^6 \text{ cm}^{-2} \text{ s}^{-1}$
Bunch spacing	Higgs: 680 ns; W: 210 ns; Z: 25 ns

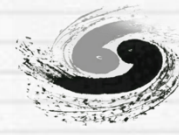




A generic simulation framework for **semiconductor tracker** and **vertex detectors**:

- Reflect the physics:
 - A run consists of several sequential events. A single event here refers to an independent passage of one or multiple particles through the setup.
 - Detectors are treated as separate objects for particles to pass through.
 - All relevant information must be contained at the end of processing every single event (sequential events).
- Ease of use:
 - Simple, intuitive configuration and execution (“does what you expect”).
 - Clear and extensive logging and error reporting capabilities.
 - Implementing a new module should be feasible without knowing all details of the framework.
- Flexibility
-

Provide a complete and easy-to-use package to us for simulating the performance of detectors from incident ionizing radiation until the digitization of hits in the detector chip.

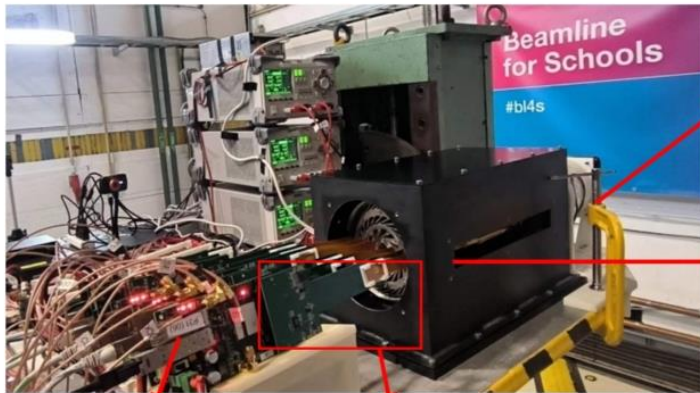
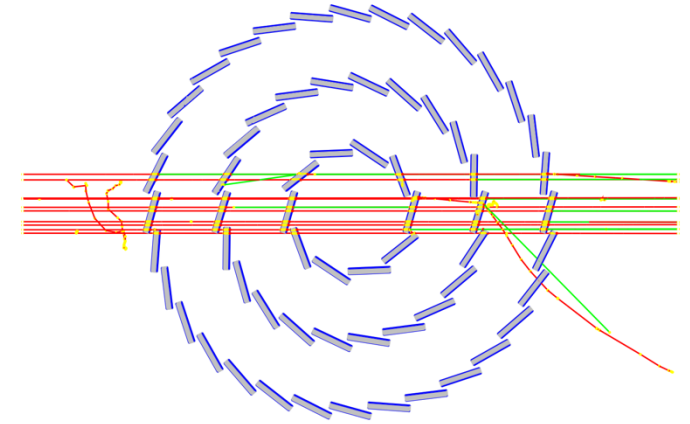


We run the beam test of VXD Prototype in 2023.4

- The 4 - 6 GeV electron beam provided by DESY II.
- The cooling system brought the temperature of the prototype from 40° C to 28° C, ensuring the prototype's good performance.

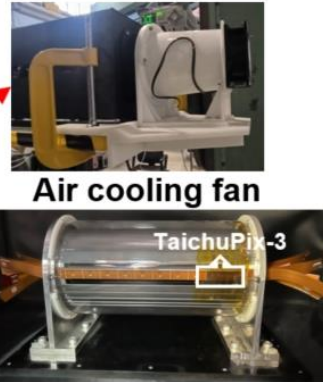
During the data collection period

- The electronic readout system and data acquisition system operated stably.
- Maximum data rate 18Mb/s



FPGA board

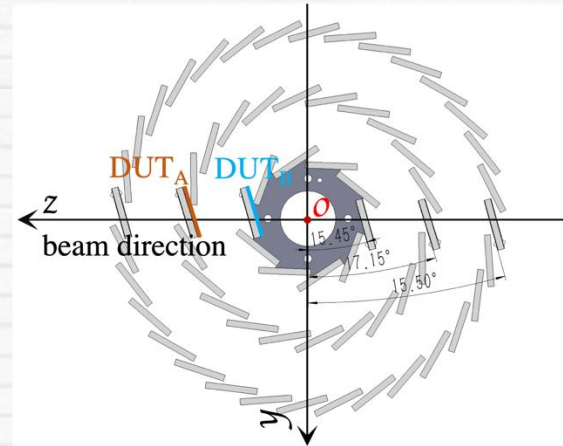
Interposer board



Air cooling fan

TaichuPix-3

Baseline vertex detector prototype

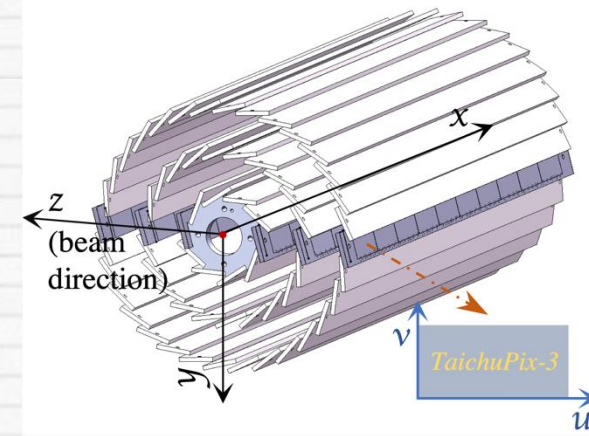


DUT_A

DUT_B

z
beam direction

y

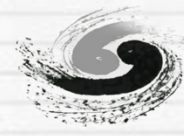


z
(beam direction)

TaichuPix-3

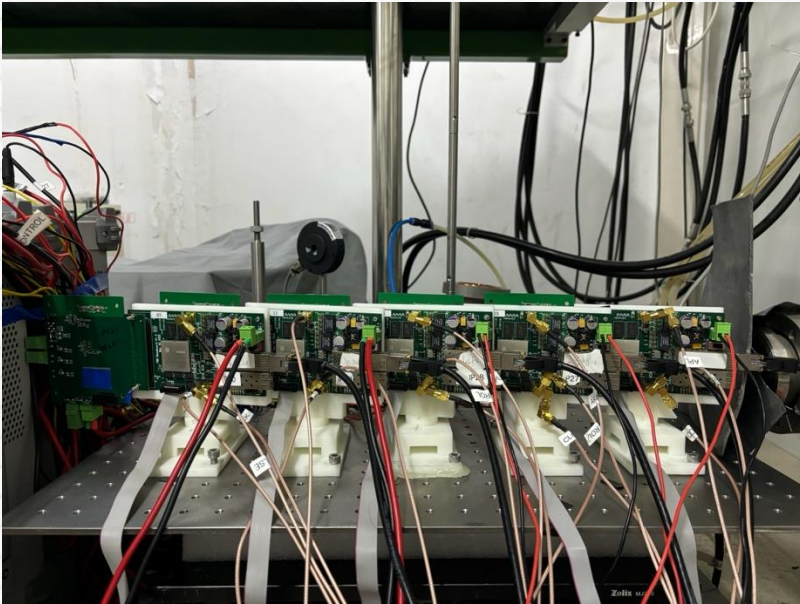
u

Intro: Angle Beam Test

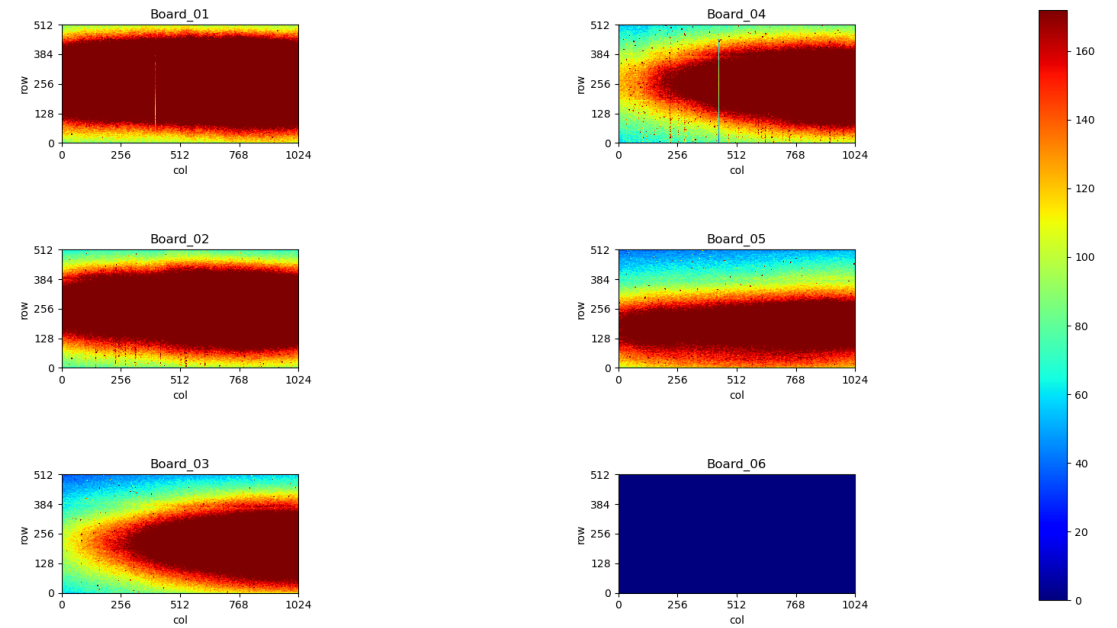


Setup the TaichuPix-3 telescope with tilt angle (80° , 70° , 60°)

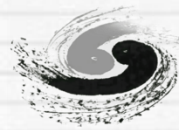
- Synchrotron pattern (about 0.5 mm Pb to shield the X ray)
- 2.5 GeV e^- (data rate: $\sim 4\text{-}7$ Mb/s)
- Tilt angle of 5 test boards: (80° , 70° , 60°) * 5
- Threshold of 5 test boards: 32, 32, 32 (64, 96), 32, 32



There is no much room to put sixth test board

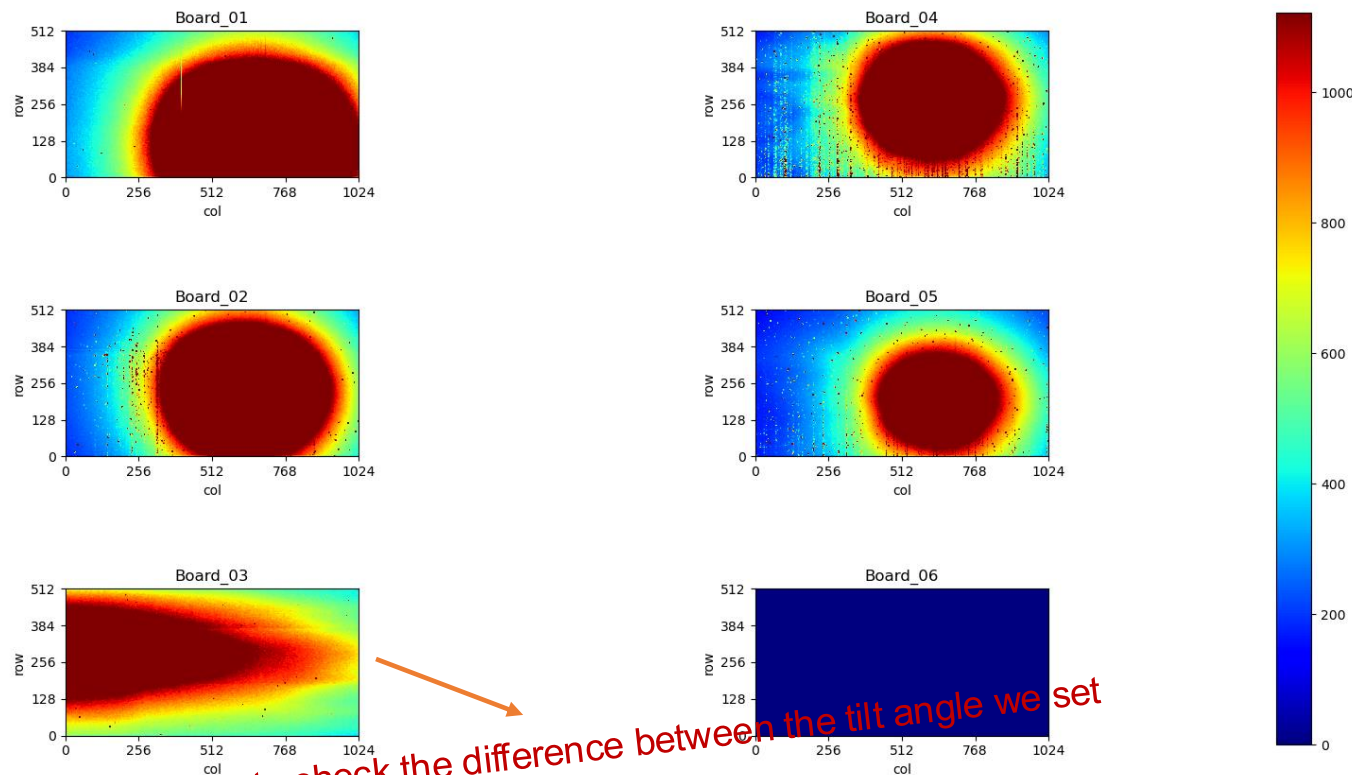
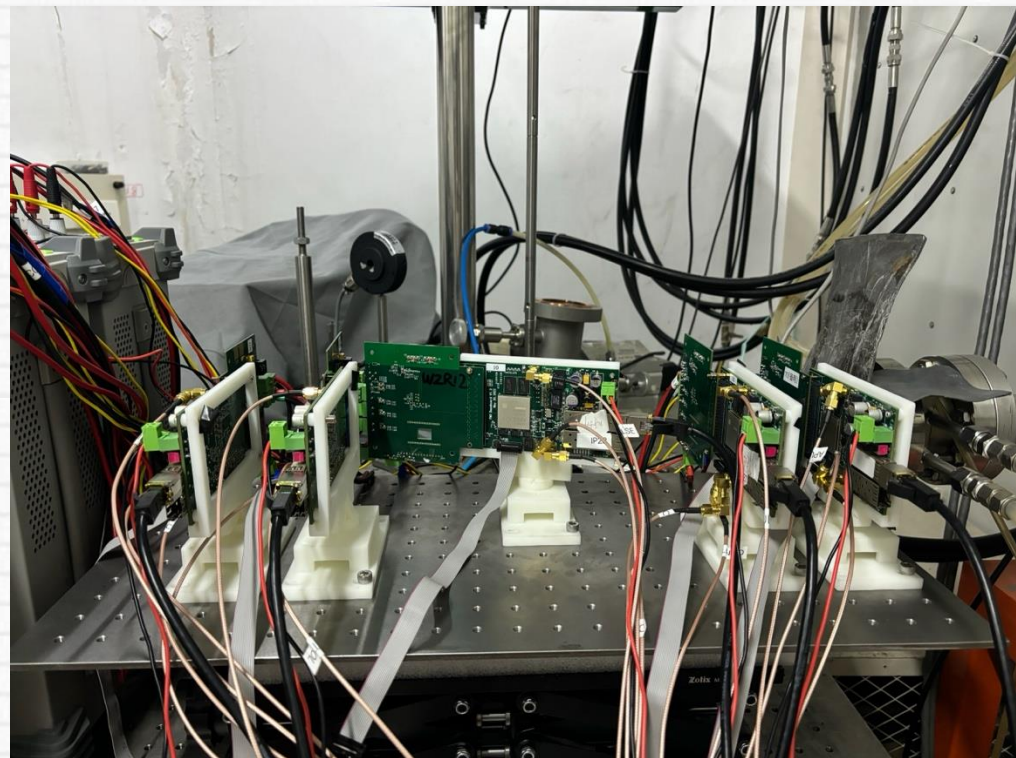


Intro: Angle Beam Test



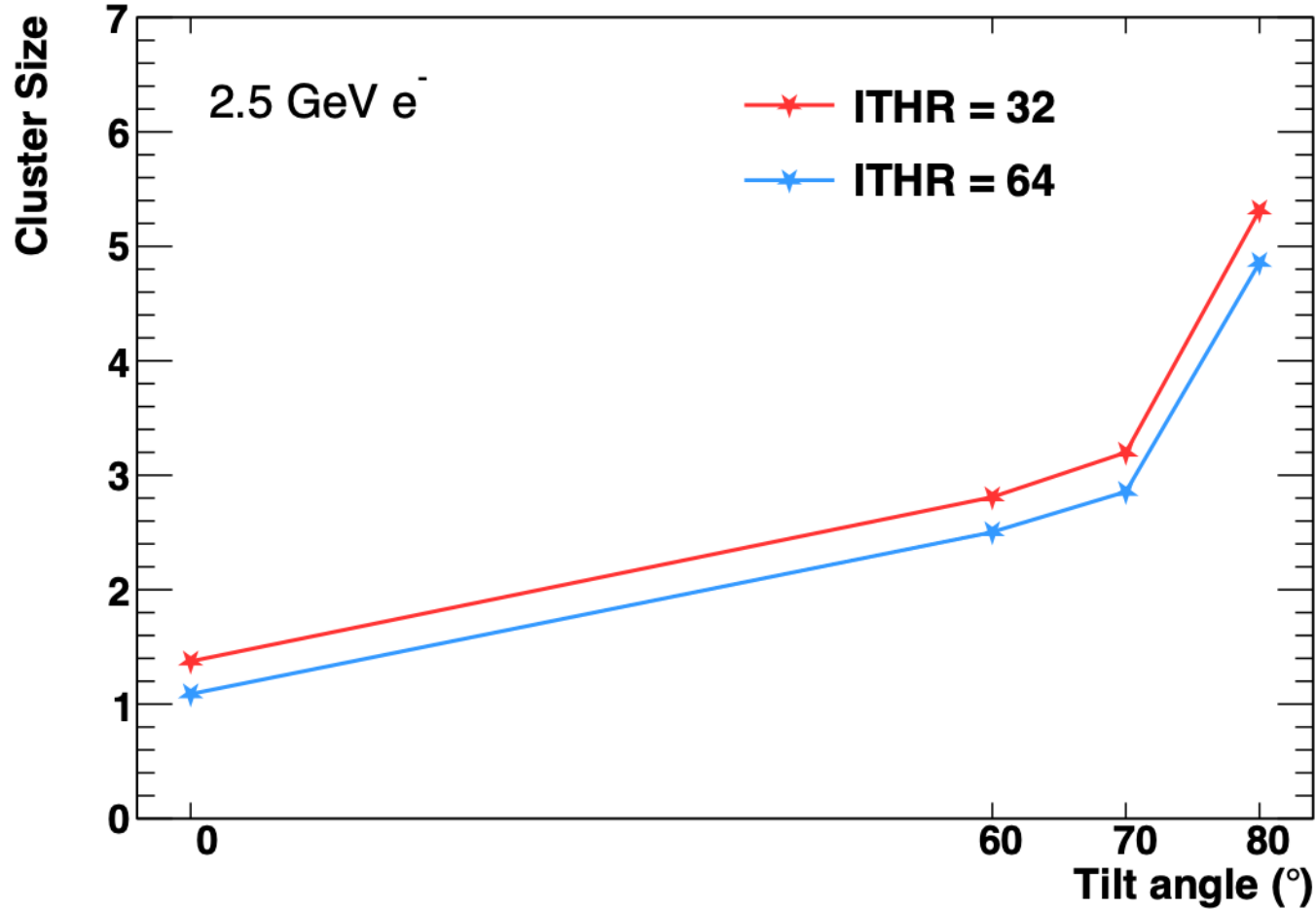
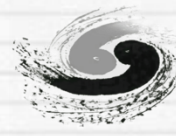
- Tilt angle: 0° , 0° , 80° , 0° , 0°
- Threshold: 32, 32, 32 (64, 96), 32, 32

Multiple scattering from the medium PCB board, which makes it difficult to reconstruct the tracks.



Allow us to check the difference between the tilt angle we set and the real tilt angle

Result: Beam Test(Cluster Size)

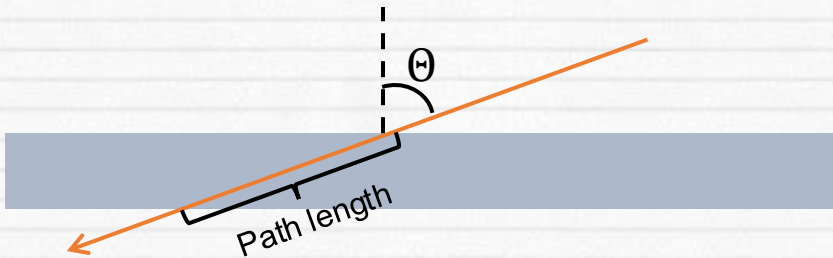


Angle	ITHR32	ITHR64
0°	1.561	1.469
16°	1.645	1.478
60°	2.809	2.504
70°	3.199	2.856
80°	5.315	4.857

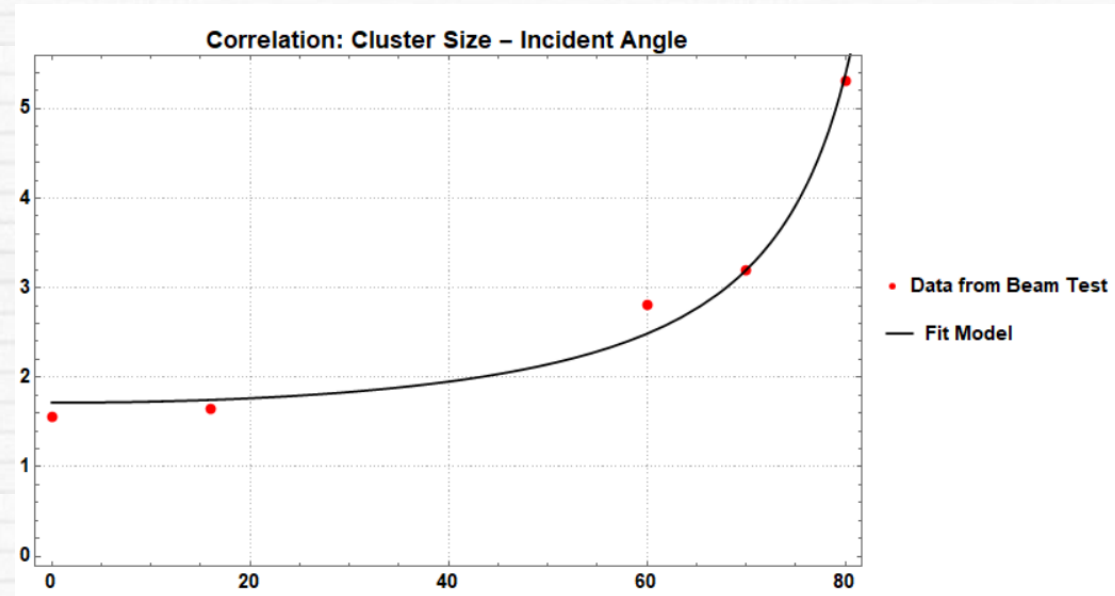
from prototype beam test at DESYII.

Test environment at DESYII is similar with this time. It can be used for analysis.

Cluster size correlate with the length of a particle's path through the detector.

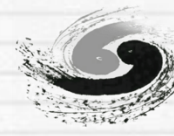


$$\text{Cluster size} = a \sec \theta + b$$

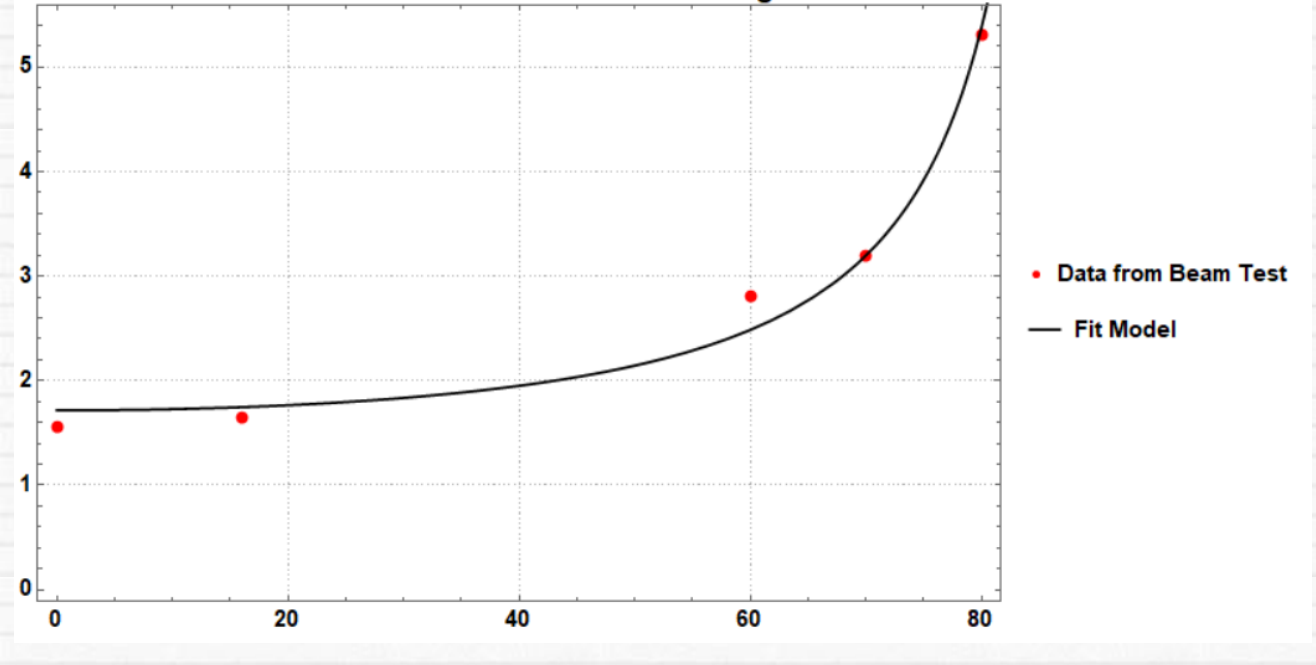


x-axis label is incident angle in degree, and y-axis label is cluster size.

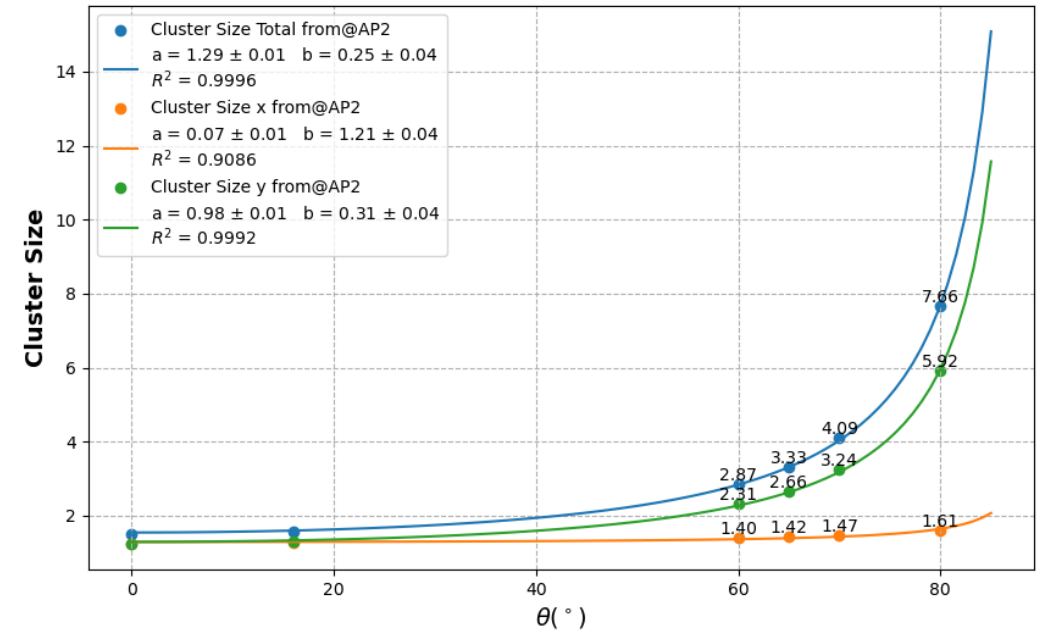
Param	Estimate	Std Error	RSquared
b	0.945	0.172	0.9972
a	0.770	0.056	



Correlation: Cluster Size – Incident Angle



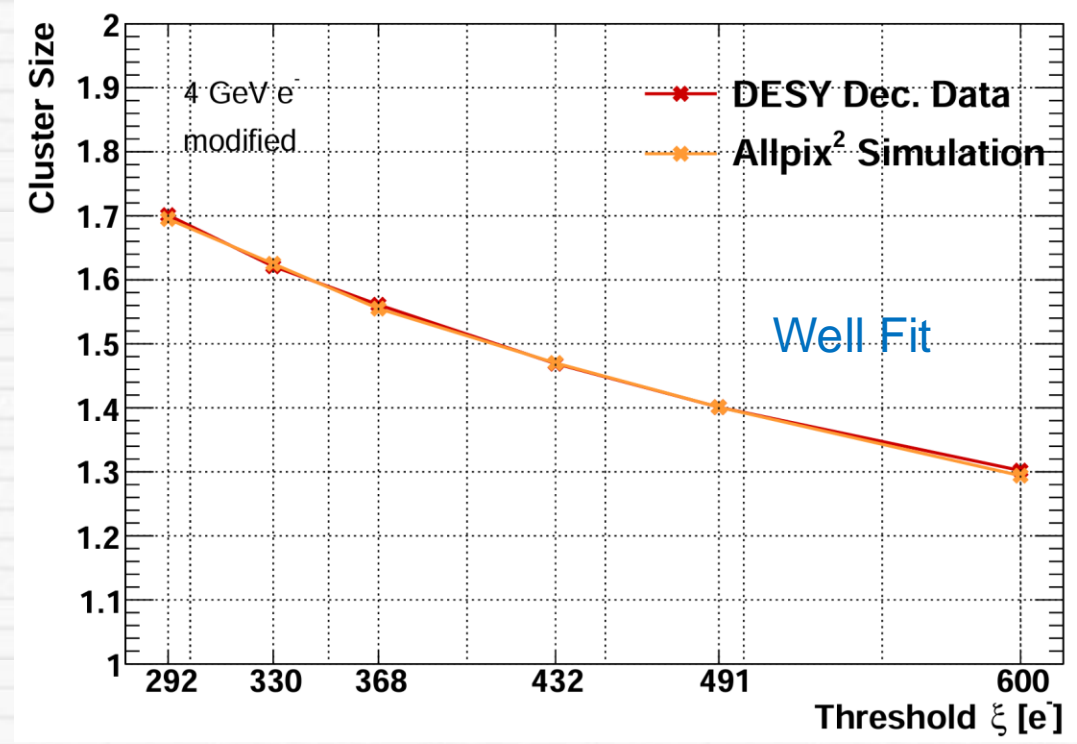
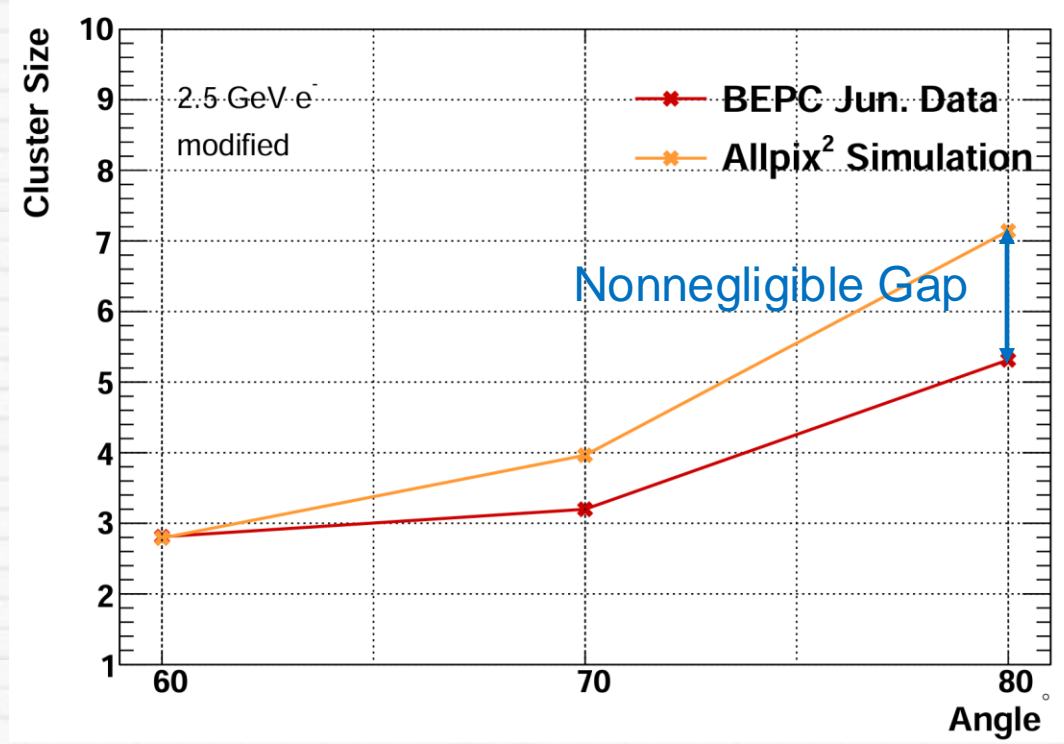
AP2 Sim Result



The picture at right hand is the data generated by AllPix-2 to verify our model.
The setting of the tilt angle may have some errors compared to the expectation.

Gives us reason to re-examine the actual value.

Analysis: BeamTest vs. AllPix-2

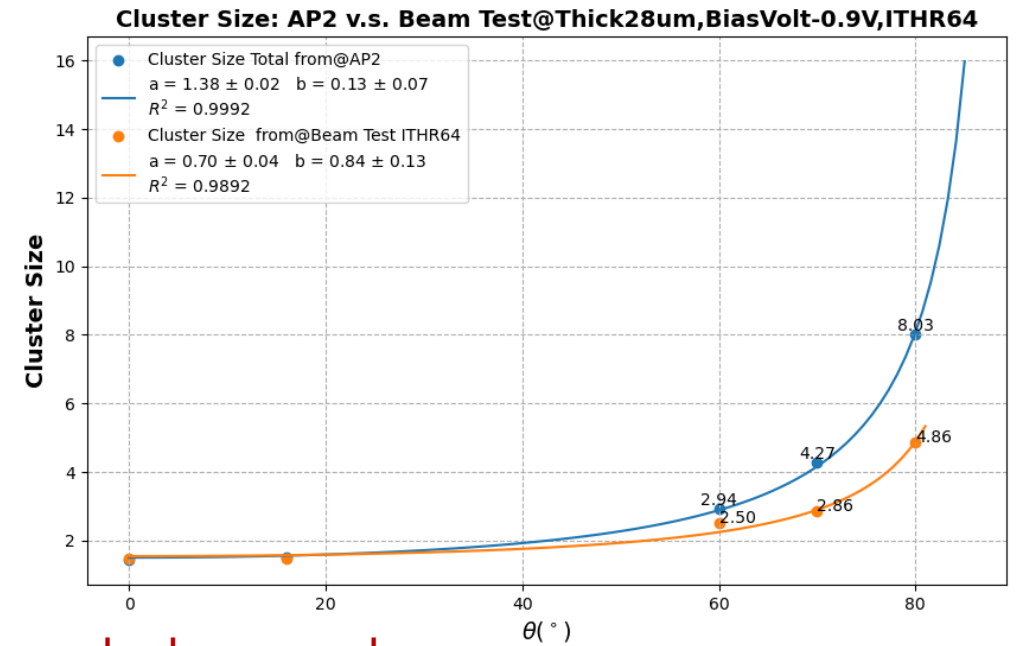
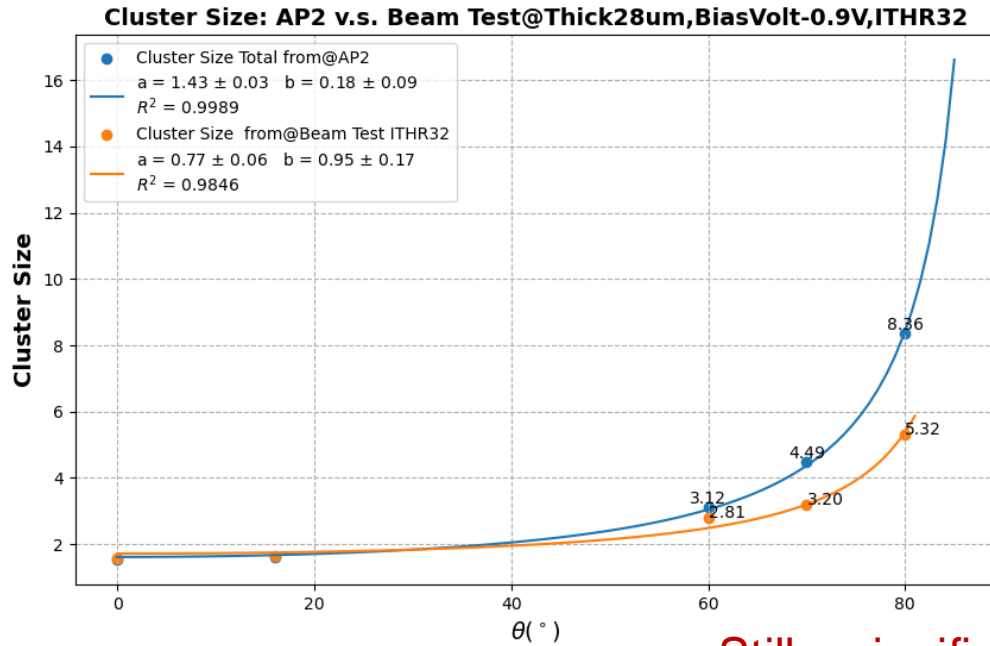
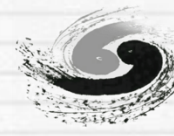


AP2 sim requirement:

- Electric field distribution
- Sensor geometry
- Support geometry
- Source energy
-

Main parameters:

- Linear, bias voltage: -0.9V → employed as an approximation
- Sensor thickness: 28um, angle...
- Threshold: 368 e^- → ITHR32, 432 e^- → ITHR64 ...
-

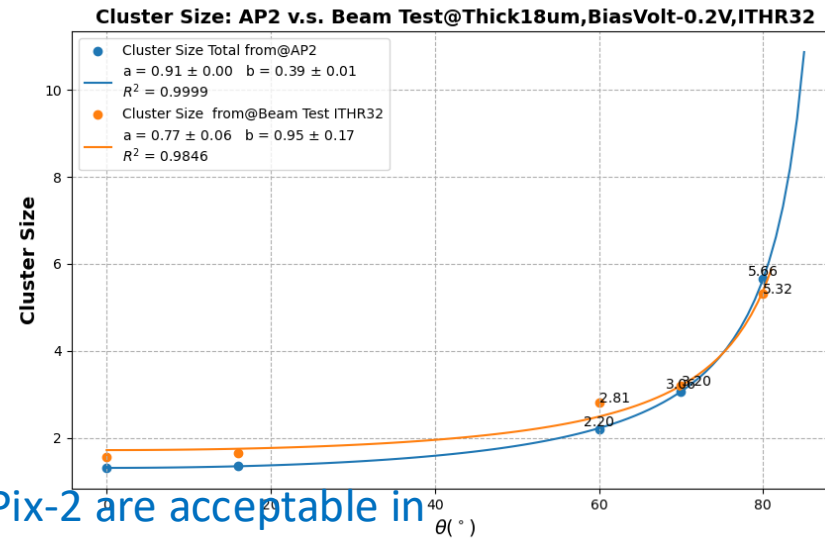
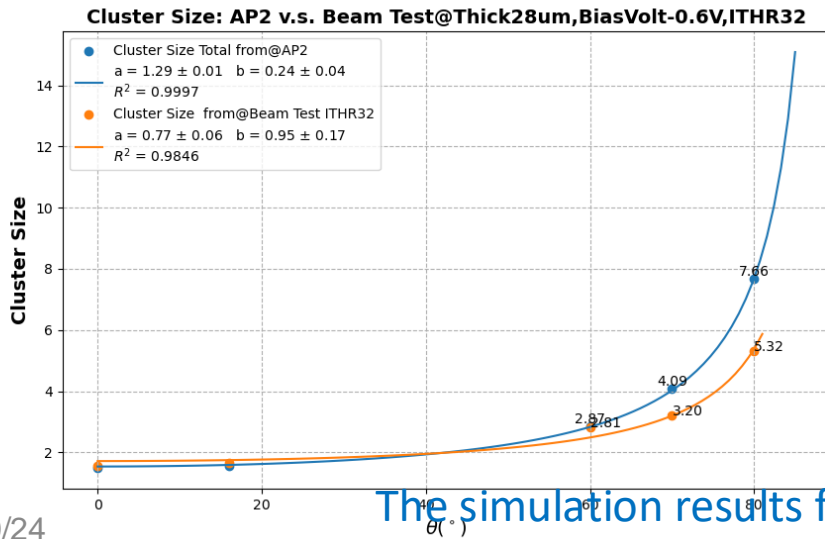
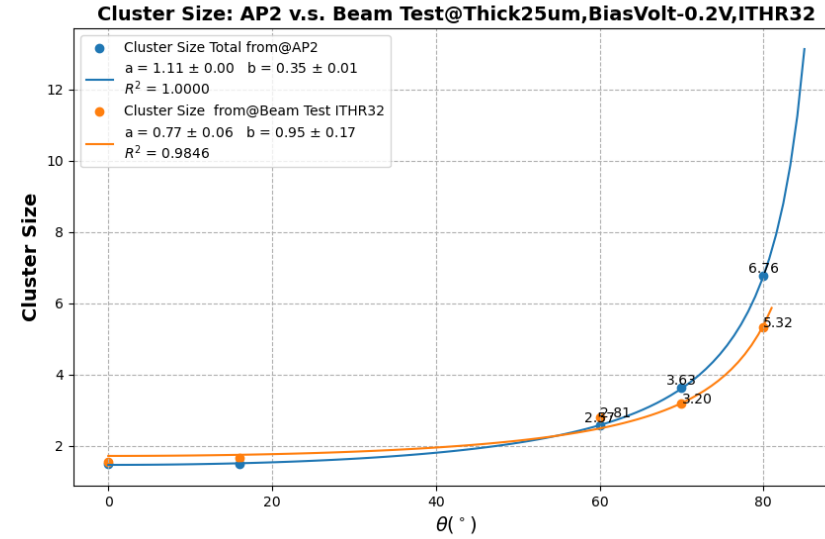
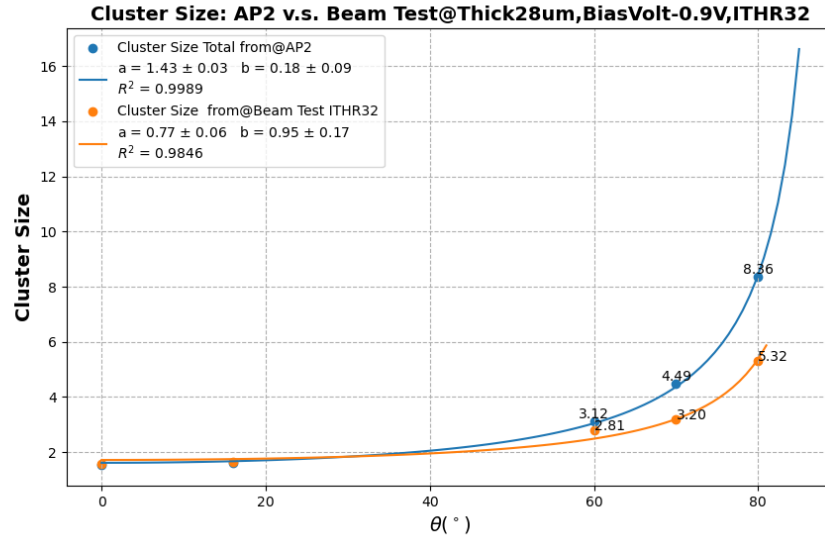
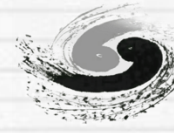


Still a significant difference under large angle.

- In AllPix-2, signals produced by substrate does not contribute.
- Due to electric field distributions, the effective sensitive thickness may differ from the marked thickness.

Adjusting the thickness parameter is acceptable.

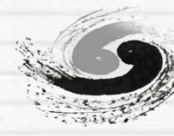
Analysis: Further Attempts



Reducing the thickness and bias voltage

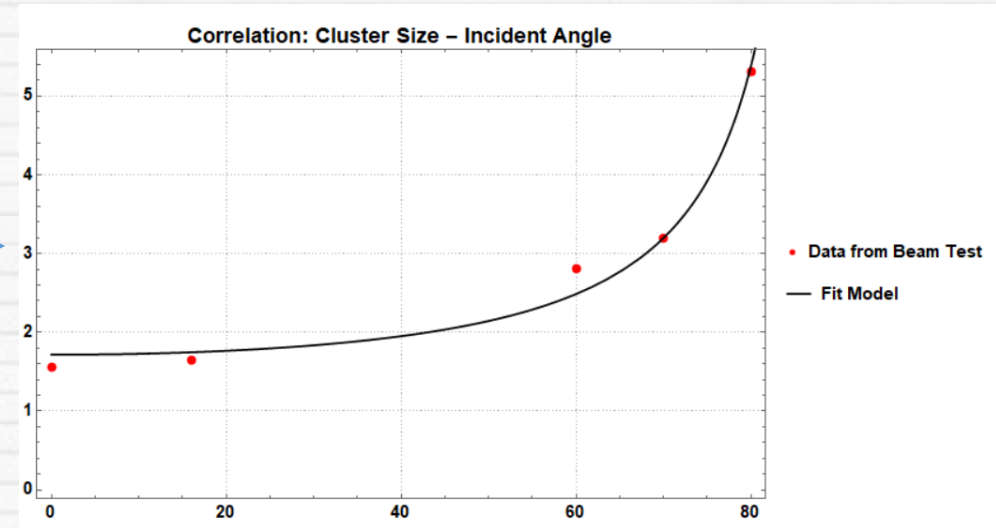
Reducing the electric field bias

The simulation results from AllPix-2 are acceptable in comparison to the experimental measurement results.



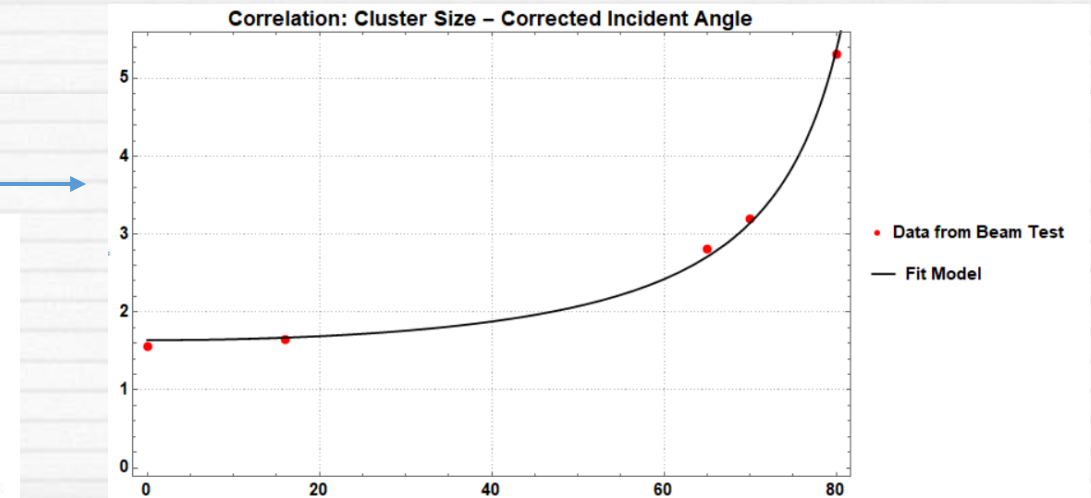
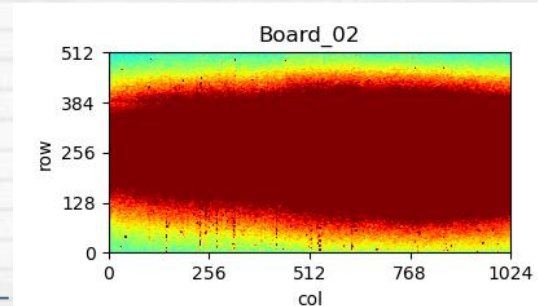
Regarding the differences in the simulation results, our analysis has following weakness:

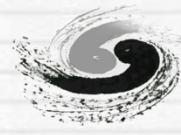
- Electric field distribution is unclear now.
- The true value of the incident angle may differ from the currently adopted value. →
- The geometrical details of the supporting structure and other components are not refined.



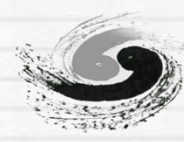
What's more, the following improvements can be made in the future:

- Electric field distribution should be measured or calculated precisely.
- Verify the incident angle and other relevant information through the hit map. →
- Refined the current geometry.

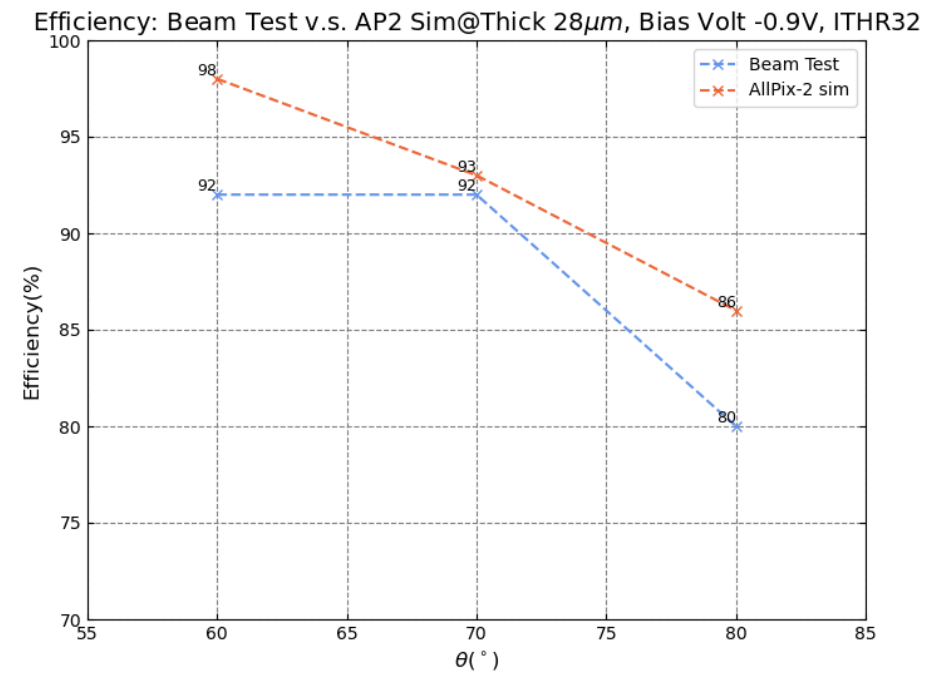
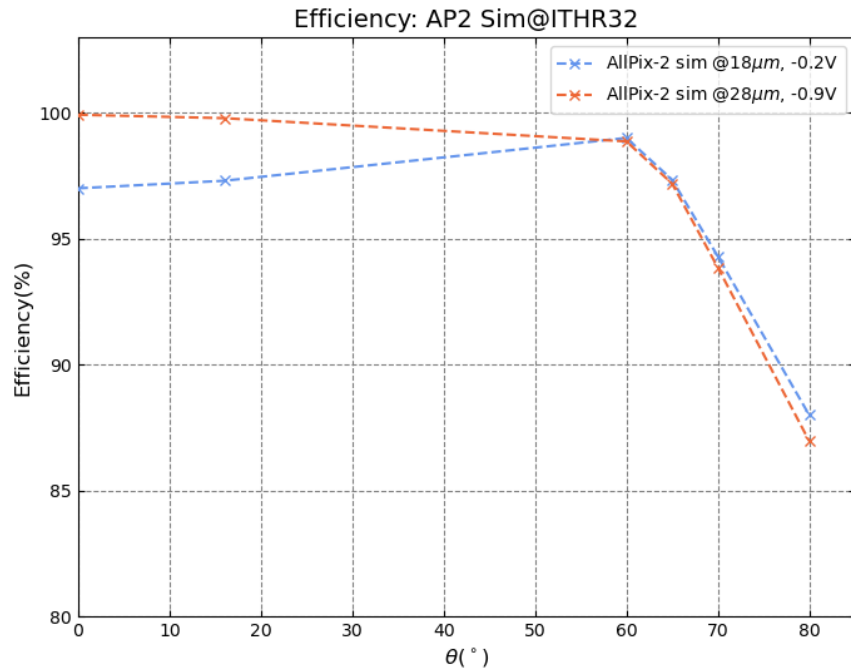


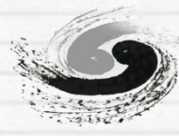


- Conduct more in-depth tests on TaichuPix-3:
 - Incident Angle - Efficiency,
 - Incident Angle - Spatial Resolution,
 - Cluster Size - Spatial Resolution
- Conduct more precise measurements at refined angles.
- Connect AllPix-Squared with CEPCSW for digitization.
-



Due to issues with the experimental environment, the alignment of the experimental data could not be performed this time, making it impossible to calculate the efficiency precisely. The actual results are expected to be higher than the current calculated results. The experimental data provided here are for reference only.





中國科學院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

Thanks for Your Attention!